

N-Channel Super Junction Power MOSFET $\,\,{\rm IV}$

General Description

The series of devices use advanced trench gate super junction technology and design to provide excellent R_{DS(ON)} with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

Features

- Optimized body diode reverse recovery performance
- •Low on-resistance and low conduction losses
- Small package
- ●Ultra Low Gate Charge cause lower driving requirements
- 100% Avalanche Tested
- ●ROHS compliant

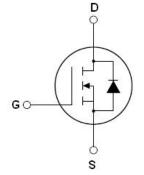
Application

- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)
- LLC Half-bridge

Package Marking And Ordering Information

Device	Device Package	Marking
NCE60N700I	TO-251-3L	NCE60N700I

V_{DS min@Tjmax} 650 V R_{DS(ON)TYP} 650 mΩ ID 6.1 A Qg 9.6 nC



Schematic diagram



Table 1. Absolute Maximum Ratings (Tc=25°C)

Parameter	Symbol	Value	Unit
Drain-Source Voltage (VGS=0V)	Vds	600	V
Gate-Source Voltage (VDS=0V) AC (f>1 Hz)	Vgs	±30	V
Gate-Source Voltage (VDS=0V) DC	Vgs	±20	V
Continuous Drain Current at Tc=25°C	I _{D (DC)}	6.1	А
Continuous Drain Current at Tc=100°C	I _{D (DC)}	4.27	A
Pulsed drain current (Note 1)	I _{DM (pluse)}	18.3	A
Maximum Power Dissipation(Tc=25°C)	PD	68	W
Derate above 25°C		0.45	W/°C
Avalanche current ^(Note 1)	I _{AS}	1.3	A
Drain Source voltage slope, V _{DS} ≤480 V,	dv/dt	50	V/ns
Reverse diode dv/dt, V _{DS} ≤480 V,I _{SD} <i<sub>D</i<sub>	dv/dt	15	V/ns
Operating Junction and Storage Temperature Range	TJ,TSTG	-55+175	°C

* limited by maximum junction temperature



Table 2. Thermal Characteristic

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case (Maximum)	R _{thJC}	2.20	°C /W
Thermal Resistance, Junction-to-Ambient (Maximum)	R _{thJA}	62	°C /W

Table 3. Electrical Characteristics (TA=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
On/off states				•		
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250µA	600			V
Zero Gate Voltage Drain Current(Tc=25°C)	I _{DSS}	V _{DS} =600V,V _{GS} =0V			1	μA
Zero Gate Voltage Drain Current(Tc=125℃)	I _{DSS}	V _{DS} =600V,V _{GS} =0V			100	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V			±200	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =250µA	3	3.5	4	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =3A		650	700	mΩ
Dynamic Characteristics		· · · · · ·				
Input Capacitance	Clss			250		pF
Output Capacitance	Coss	V _{DS} =50V,V _{GS} =0V, F=1.0MHz		21		pF
Reverse Transfer Capacitance	C _{rss}	F=1.0MHZ		4		pF
Total Gate Charge	Qg			9.6		nC
Gate-Source Charge	Qgs	V _{DS} =450V,I _D =3A, V _{GS} =10V		2.5		nC
Gate-Drain Charge	Q _{gd}			3.3		nC
Gate plateau voltage	Vgp			5.5		V
Intrinsic gate resistance	Rg	f = 1 MHz open drain		43		Ω
Switching times	'					
Turn-on Delay Time	t _{d(on)}			11		nS
Turn-on Rise Time	tr	V _{DD} =380V,I _D =3A,		6		nS
Turn-Off Delay Time	t _{d(off)}	R _G =1.7Ω,V _{GS} =10V		26		nS
Turn-Off Fall Time	t _f			10		nS
Source- Drain Diode Characteristics						
Source-drain current(Body Diode)	I _{SD}	T OF O			6.1	А
Pulsed Source-drain current(Body Diode)	I _{SDM}	Tc=25°C			18.3	А
Forward On Voltage	V _{SD}	Tj=25°C,I _{SD} =6.1A,V _{GS} =0V		0.9	1.2	V
Reverse Recovery Time	t _{rr}			140		nS
Reverse Recovery Charge	Qrr	Tj=25°C,I⊧=3A,		0.64		uC
Peak Reverse Recovery Current	Irrm	di/dt=100A/µs		9		А

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature

2. Tj=25°C,VDD=50V,VG=10V, R_G=25 Ω



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

Figure1. Safe operating area

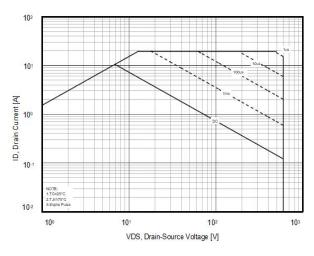


Figure3. Transfer characteristics

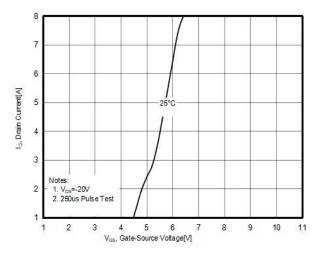


Figure 5. RDS(ON) vs Junction Temperature

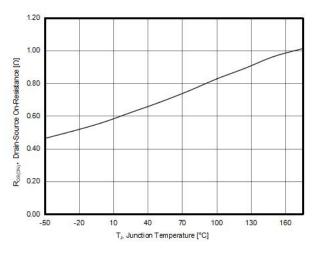


Figure2. Capacitance

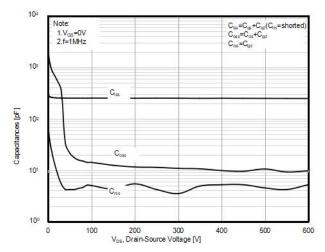


Figure4. Output characteristics

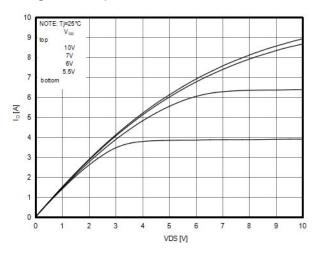


Figure6. BV_{DSS} vs Junction Temperature

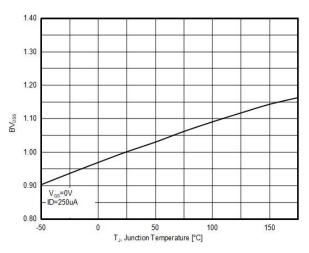




Figure7. Maximum I_D vs Junction Temperature

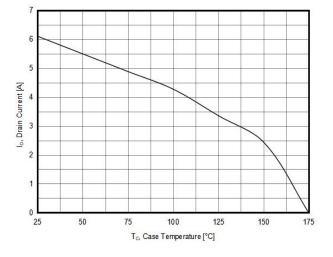


Figure8. Gate charge waveforms

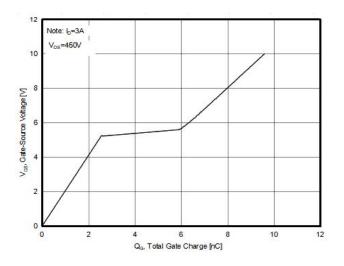


Figure9. Static drain-source on resistance

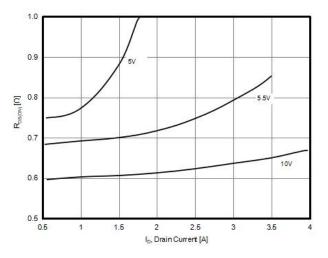
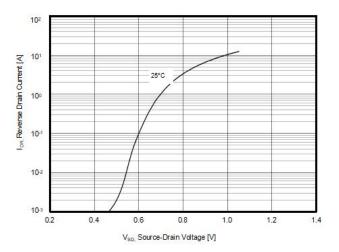


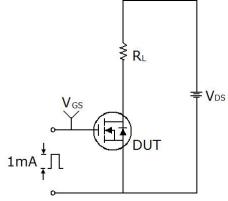
Figure10. Source-Drain Diode Forward Voltage

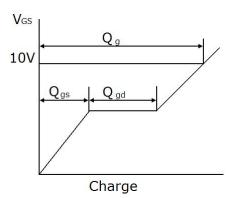




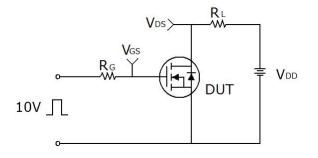
Test circuit

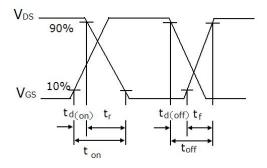
1) Gate charge test circuit & Waveform



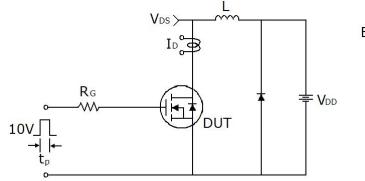


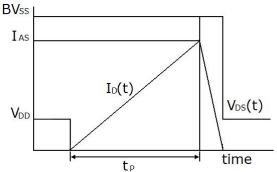
2) Switch Time Test Circuit:





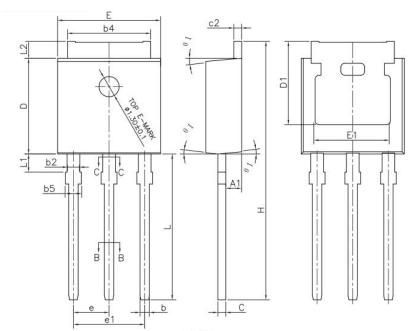
3) Unclamped Inductive Switching Test Circuit & Waveforms







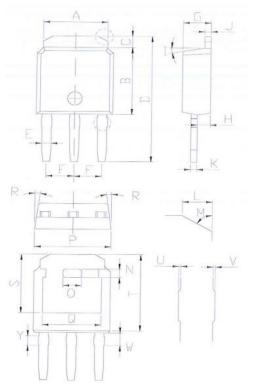
TO-251-3L-P Package Information



Symbol	Dimensions	In Millimeters	Dimensions In Inches		
	Min.	Max.	Min.	Max.	
А	2.20	2.35	0.087	0.093	
A1	0.90	1.10	0.035	0.043	
b	0.56	0.69	0.022	0.027	
b1	0.55	0.65	0.022	0.026	
b2	0.77	0.90	0.030	0.035	
b3	0.76	0.86	0.030	0.034	
b4	5.23	5.43	0.206	0.214	
b5		1.05		0.041	
С	0.46	0.59	0.018	0.023	
c1	0.45	0.55	0.018	0.022	
c2	0.46	0.59	0.018	0.023	
D	6.00	6.20	0.236	0.244	
D1	5.20		0.205		
E	6.50	6.70	0.256	0.264	
E1	4.60	5.00	0.181	0.197	
е	2.24	2.34	0.088	0.092	
e1	4.47	4.67	0.176	0.184	
Н	16.18	16.78	0.637	0.661	
L	9.00	9.60	0.354	0.378	
L1	0.95	1.35	0.037	0.053	
L2	0.90	1.25	0.035	0.049	



TO-251-3L-L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
А	5.04	5.64	0.198	0.222
В	5.70	6.30	0.224	0.248
С	0.75	1.35	0.030	0.053
D	11.01	11.61	0.433	0.457
E	0.61	0.91	0.024	0.036
F	2.13	2.43	0.084	0.096
G	2.00	2.60	0.079	0.102
Н	0.76	1.36	0.030	0.054
J	0.36	0.66	0.014	0.026
K	0.37	0.67	0.015	0.026
L	0.50	1.10	0.020	0.043
Ν	0.45	1.05	0.018	0.041
0	1.50	2.10	0.059	0.083
Р	6.30	6.90	0.248	0.272
Q	4.55	5.15	0.179	0.203
S	5.00	5.60	0.197	0.220
Т	6.60	7.20	0.260	0.283
W	0.90	1.40	0.035	0.055
Y	0.60	1.10	0.024	0.043



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